imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Vishay Siliconix

Dual N-Channel 12-V (D-S) MOSFET

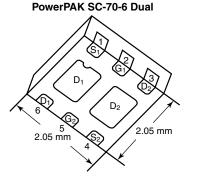
PRODUCT SUMMARY						
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
12	0.040 at V _{GS} = 4.5 V	4.5				
	0.048 at V _{GS} = 2.5 V	4.5	4.5 nC			
	0.063 at V _{GS} = 1.8 V	4.5				

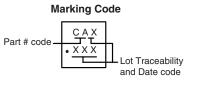


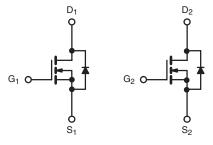
- Halogen-free
- TrenchFET[®] Power MOSFET
- New Thermally Enhaced PowerPAK® SC-70 Package
 - Small Footprint Area

APPLICATIONS

Load Switch for Portable Applications







N-Channel MOSFET

Ordering Information: SiA912DJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted Symbol Unit Parameter Limit **Drain-Source Voltage** V_{DS} 12 V V_{GS} Gate-Source Voltage ± 8 _C = 25 °C 4.5^a T_C = 70 °C 4.5^a Continuous Drain Current (T_{.1} = 150 °C) I_D T_A = 25 °C 4.5^{a, b, c} 4.5^{a, b, c} T_A = 70 °C А Pulsed Drain Current IDM 20 T_C = 25 °C 4.5^a Continuous Source-Drain Diode Current Is T_A = 25 °C 1.6^{b, c} T_C = 25 °C 6.5 T_C = 70 °C 5 Maximum Power Dissipation P_D w T_A = 25 °C 1.9^{b, c} 1.2^{b, c} T_A = 70 °C Operating Junction and Storage Temperature Range - 55 to 150 T_J, T_{stg} °C Soldering Recommendations (Peak Temperature)^{d, e} 260

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}	t ≤ 5 s	R _{thJA}	52	65	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	12.5	16		

Notes:

a. Package limited

b. Surface Mounted on 1" x 1" FR4 board.

t = 5 s. c.

d. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components. Maximum under Steady State conditions is 110 °C/W.

f.



N-Channel MOSFET

SiA912DJ



Vishay Siliconix

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		•		•	•		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	12			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$ $\Delta V_{GS(th)}/T_J$	- Ι _D = 250 μΑ		12		mV/°C	
V _{GS(th)} Temperature Coefficient				- 2.8			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	0.4		1.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	ns	
	I _{DSS}	$V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	μA	
Zero Gate Voltage Drain Current		$V_{DS} = 12 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$			- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \leq 5$ V, V_{GS} = 4.5 V	- 20			A	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 4.2 \text{ A}$		0.033	0.040	1	
Drain-Source On-State Resistance ^a		V _{GS} = 2.5 V, I _D = 3.8 A		0.039	0.048	Ω	
		V _{GS} = 1.8 V, I _D = 1.6 A		0.051	0.063	1	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 6 V, I_{D} = 4.2 A$		13		S	
Dynamic ^b				1	1		
Input Capacitance	C _{iss}			400	1	pF	
Output Capacitance	C _{oss}	V _{DS} = 6 V, V _{GS} = 0 V, f = 1 MHz		120			
Reverse Transfer Capacitance	C _{rss}			70			
		V _{DS} = 6 V, V _{GS} = 8 V, I _D = 5.5 A		7.5	11.5	1	
Total Gate Charge	Q _g Q _{gs}	$V_{DS} = 6 V, V_{GS} = 4.5 V, I_{D} = 5.5 A$		4.5	6.8	nC	
Gate-Source Charge				0.6			
Gate-Drain Charge	Q _{gd}			0.8			
Gate Resistance	Rg	f = 1 MHz		2.5		Ω	
Turn-on Delay Time	t _{d(on)}			5	10		
Rise Time	t _r	V_{DD} = 6 V, R _L = 1.4 Ω I_D ≅ 4.4 A, V _{GEN} = 4.5 V, R _a = 1 Ω		15	25	ns	
Turn-Off Delay Time	t _{d(off)}			35	55		
Fall Time	t _f	$D = 4.4 \text{ A}, \text{ V}_{\text{GEN}} = 4.3 \text{ V}, \text{ H}_{\text{g}} = 1.22$		15	25		
Turn-on Delay Time	t _{d(on)}			5	10		
Rise Time	t _r			10	15		
Turn-Off Delay Time	t _{d(off)}	$V_{DD} = 6 V, R_L = 1.6 \Omega$ $I_D \cong 4.4 A, V_{GEN} = 8 V, R_a = 1 \Omega$		15	25		
Fall Time	t _f	$D = 4.4 \text{ A}, V_{\text{GEN}} = 6 \text{ V}, n_{g} = 1.22$		10	15		
Drain-Source Body Diode Characteristic	s			1	1		
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			4.5	A	
Pulse Diode Forward Current	I _{SM}				20		
Body Diode Voltage	V _{SD}	$I_{S} = 4.4 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			15	30	ns	
adv Diode Beverse Becovery Charge Q			8	20	nC		
Reverse Recovery Fall Time	t _a	$I_F = 4.4 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^\circ\text{C}$		8.5		ns	
Reverse Recovery Rise Time	t _b	4		6.5		1	

Notes:

a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

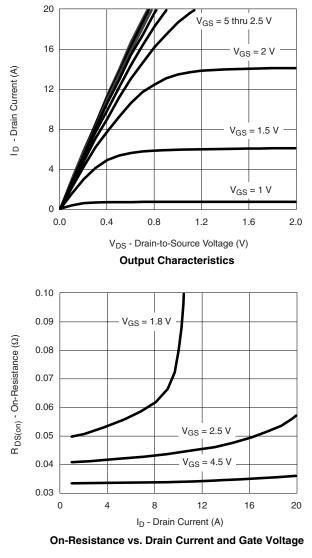
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

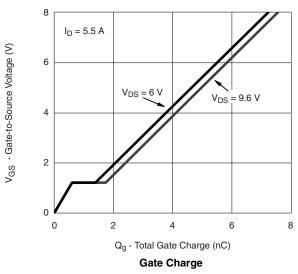


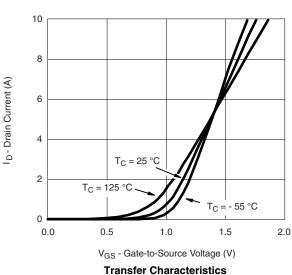


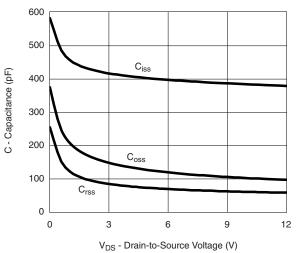
SiA912DJ Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

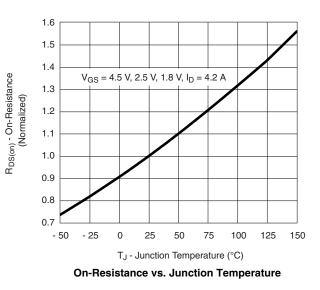












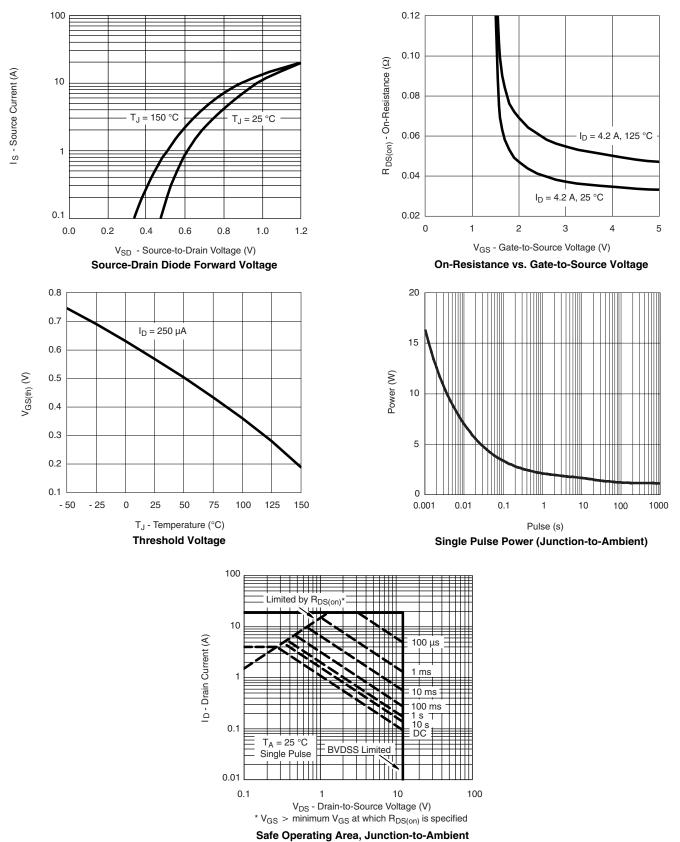
Document Number: 74953 S-80436-Rev. B, 03-Mar-08

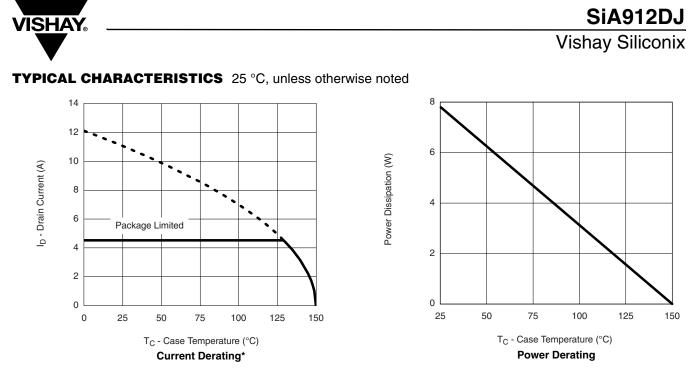
SiA912DJ



Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





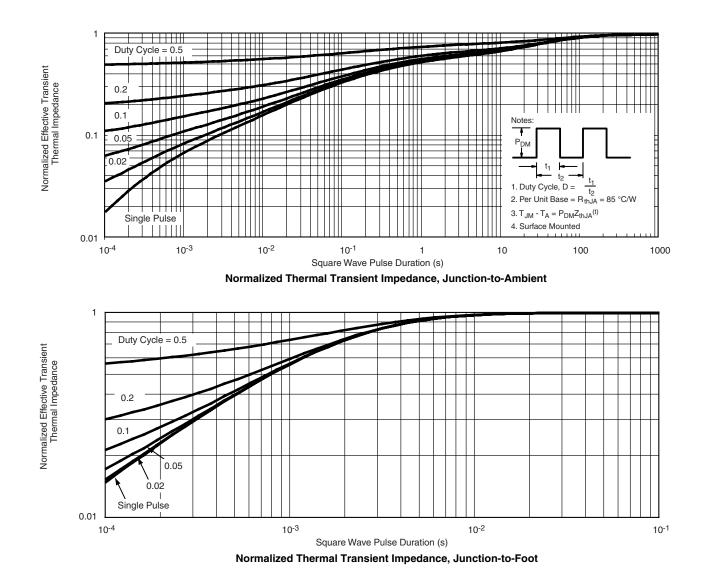
* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

SiA912DJ



Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?74953.



Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.